

ST7 AND ST9 PERFORMANCE BENCHMARKING

INTRODUCTION

STMicroelectronics has developed a set of test routines related to 8-bit and low-end 16-bit microcontroller applications to evaluate **computing performance** and **interrupt processing performance** of **microcontroller cores**. These routines have been implemented on ST7 and ST9 Microcontroller Units (MCUs) as well as several MCUs available on the market.

The routines have been written in **assembler language** to optimize their implementation and focus on core performance, without being dependent upon compiler code transformation.

For each test, the two parameters of interest are **execution time** and **code size**. Timings have been either measured whenever possible, or theoretically calculated when there was no other alternative. In most cases, programs have really run and execution times have actually been measured, so that assembly sources should not contain implementation errors and results can be considered as correct and reliable.

The results of this study point out the capability of the ST9+ to **compete with 16-bit MCUs** on 8-bit and low-end 16-bit applications and confirms its position of **high-end 8/16-bit MCU**. It also confirms the ST7 **as an outstanding 8-bit MCU**.

The first four sections provide synthetical information:

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1 OVERVIEW OF THE TEST ROUTINES

Eleven different test routines have been implemented in assembler language.

The first ten routines are oriented at measuring **core computing performance**. They are based on known algorithms and represent currently used operations in 8-bit and low-end 16-bit applications. They mix bit, 8-bit and 16-bit operations as many applications do.

This set of tests is described in Table 1.

T	ab	le	1.	Test	routine	overview
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Abbreviated name	Full name	Description	Features stressed
sieve	Eratosthenes sieve	find prime numbers \ge 3 out of 8189 elements	16-bit data computation bit manipulation
acker(m,n) ¹⁾	Ackermann function	make recursive function calls number of calls depending upon two parameters (m,n)	function calls stack use
string	String search	search a 16-byte string in a 128- character array	8-bit data block manipulation string manipulation
char	Character search	search a byte in a 40-byte array	8-bit data manipulation char manipulation
bubble(n) ²⁾	Bubble sort	sort of a one-dimension array of n 16-bit integers	16-bit data manipulation integer manipulation
blkmov(n) ³⁾	Block move	move a n-byte block from a place in memory to another	8-bit data block manipulation block move
convert	Block translation	translate a 121-byte block in a different format	8-bit data manipulation use of a lookup table
16mul	16-bit integer multiplication	multiplication of two unsigned words giving a 32-bit result	16-bit data computation integer manipulation
shright	16-bit value right shift	shift a 16-bit value five places to the right	16-bit data manipulation bit manipulation
bitsrt	Bit manipulation	set, reset, and test of 3 bits in a 128-bit array	bit computation bit and 8-bit data manipulation

1) The couple of values used are (m,n)=(3,5) and (m,n)=(3,6)

2) The values used are n=10 (words) and n=600 (words)

3) The values used are n=64 (bytes) and n=512 (bytes)

Another test routine handling a timer interrupt has been used to measure **core interrupt processing performance**:

Abbreviated name	Full name	Description	Features stressed
interrupt	Timer interrupt	standard timer input capture or/ and output compare interrupt service routine	interrupt processing

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A more precise description of the test routines is available in section 8.

2 OVERVIEW OF THE MCU CORES

The set of MCUs evaluated is composed of various **8-bit**, **8/16-bit**, **and 16-bit microcontrollers** with accumulator, register file or mixed architectures.

Table 2 is an overview of the MCU cores.

Table 2. MCU cores overview

MCU name	Architecture	Short core description	Freq ¹⁾
80C51XA PHILIPS	16-bit; register file	eXtended Architecture (XA) of 80C51's - upward compatible 8/16-bit register bus - 16-bit data/program memory buses register file programming model with sixteen 16-bit banked registers	20 MHz
68HC16 MOTOROLA	16-bit; two accumulators	core architecture superset of 68HC11's - upward compatible accumulator programming model with two 16-bit accumulators, and three 16-bit index registers (all with 4-bit extensions)	16 MHz
68HC12 MOTOROLA	16-bit; two accumulators	instruction set is superset of 68HC11's - upward compatible programming model identical to 68HC11's	8 MHz
ST9+ STMicroelectronics	8/16-bit; register file	evolution of the ST9 enhanced clock speed, instruction cycle time enlarged memory space	25 MHz
ST9 STMicroelectronics	8/16-bit; register file	8/16-bit architecture; 8-bit register bus - 16-bit memory bus register file programming model with 14 groups of sixteen 8-bit registers, useable as 16-bit registers modular paged registers for access to peripheral registers	12 MHz
H8/300 HITACHI	8/16-bit; register file	RISC-like architecture and instruction set register file programming model with sixteen 8-bit registers	10 MHz
68HC11 MOTOROLA	8-bit; two accumulators	market standard 8-bit MCU accumulator programming model with two 8-bit accumulators or one 16-bit accumulator, and two 16-bit index registers	4 MHz
68HC08 MOTOROLA	8-bit; accumulator	superset of the 68HC05 - upward compatible enhanced performance and instruction set accumulator programming model with one 8-bit accumulator, and one 16-bit index register	8 MHz
ST7 STMicroelectronics	8-bit; accumulator	upward compatible with the 68HC05 accumulator programming model with one 8-bit accumulator, and two 8-bit index registers	4 MHz 8 MHz
80C51 INTEL, PHILIPS	8-bit; register file and accumulator	mixed accumulator and register file programming model with four banks of eight 8-bit registers (include accumulator), and a 16-bit data pointer	20 MHz
KS88 SAMSUNG	8-bit; register file	core architecture superset of SUPER8's; 8-bit register bus register file programming model with 192 8-bit prime data registers, and two register sets with system/peripheral/data registers	8 MHz
78K0 NEC	8-bit; register file and accumulator	mixed accumulator and register file programming model with four banks of eight 8-bit or four 16-bit registers (include accumulator) each MCU core, the maximum internal frequency (Freq) available, for eac	10 MHz

development board has been used (unless other specified). Note that results are directly proportional to this frequency.

A description of the MCU work environments is available in section 5.

3 BENCHMARK RESULTS

3.1 CORE COMPUTING PERFORMANCE

The two following charts show benchmark results for computing performance. Execution time and code size are presented as **global ratios** taken the **ST9+ as reference**.

Preliminary ratios have been calculated for each test. Using those results, a global execution time ratio and a global code size ratio have been calculated as an average of all ratios. As all the tests could not have been implemented on all MCUs (see <ltalic>9.2.2 Memory considerations<ltalic end>), one or two different results are presented for each MCU. The first one, available for all the MCUs, has been calculated with the reduced set of tests performed on all the MCUs. The second one, only available for some MCUs, has been calculated with the full set of tests.

Refer to section 6 for complete results. Refer to section 9 for measurement proceeding and calculation description.

Figure 1. presents execution time ratios and Figure 2. shows code size ratios.

Notes: The reduced set of tests is composed of:

string, char, bubble(10 words), blkmov(64 bytes), convert, 16mul, shright, bitrst

The full set of tests is composed of:

string, char, bubble(10 words), blkmov(64 bytes), convert, 16mul, shright, bitrst, sieve, acker(3,5), acker(3,6), bubble(600 words), blkmov(512 bytes)

The 80C51 results are preliminary results. They may change in later versions.





3.2 CORE INTERRUPT PROCESSING PERFORMANCE

The three following charts show benchmark results for interrupt processing performance. Execution time results are presented as **time values** (in microseconds), and also as **ratios** taken the **ST9+ as reference**. Code size results are presented as **ratios** taken the **ST9+ as reference**.

Refer to section 6 for complete results and details on calculation.

Figure 3. presents execution time results in microseconds, showing interrupt latency & return time.

Figure 4. presents execution time ratios, and Figure 5. presents code size ratios.







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sUOM 11d-01

4 RESULT ANALYSIS

This section is an analysis of **computing performance** and **interrupt processing performance** results (for execution time and code size). Based on core architecture analysis (see section 7), two comparisons are presented, pointing out the strong and weak points of each MCU. The first concerns the **high-end to medium-end MCUs versus ST9+**. The second concerns the **medium-end to low-end MCUs versus ST7**.

4.1 PRELIMINARY REMARK

Results show that the two different ratios, for execution time and code size, calculated with full and reduced sets of tests, are in fact not very different. In most cases, the classification of the MCUs is kept. Thus we can consider that **the reduced set is sufficient** to make the MCU core comparison.

4.2 HIGH-END TO MEDIUM-END MCU ANALYSIS VERSUS ST9+

The Table 3 presents the strong and the weak points for high-end to medium-end MCUs, compared to the ST9+ MCU.

Notes: ICT means Instruction Cycle Time and IL means Instruction Length.

Refer to paragraph <Italic>7.2.2 Average ICT/CPI and IL<Italic end> for details on calculation.

Refer to paragraph < Italic>7.3.4 ST9+ MCU core< Italic end> to see the main characteristics of the ST9+ MCU core.

4.2.1 Computing performance results

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Regarding speed, the ST9+ MCU ranks at the top of 8/16-bit MCUs. This new version of the ST9 has been improved on several points, including clock per instruction and clock speed. These enhancements have considerably reduced its instruction cycle time. A large and powerful register file organized in groups allow the ST9+ to perform strong computation (with many registers), have an easy access to peripheral and i/o port registers (with paged registers), and manage multitasking (with register group pointers). Addressing modes like register pair, register indirect with pre/post-increment, and indexed give the ST9+ the ability to perform 16-bit data computation and manipulation, easily manipulate tables and move blocks. A new memory management unit enlarges the memory space up to 4 Mbytes. New instructions have been added to handle this new space and improve the C-language support.

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Concerning code efficiency, the position of the ST9+ MCU is also **among the best MCUs**. The 16-bit MCUs are only a little better, although favoured by their true 16-bit computing and data manipulation instructions. In the 8/16-bit MCUs, the H8/300 takes a little advantage due to its special block move instruction. But all 8-bit MCUs, even with shorter instruction lengths, have longer code size results.

4.2.2 Interrupt processing performance results

Regarding speed, the ST9+ MCU ranks **at the first position**. The value chart shows that it has the **shortest interrupt latency** but also an interrupt routine execution time which is among the best. These results show that its interruption management and instruction cycle time have been considerably enhanced. The register groups bring in addition **fast context switching** capabilities.

Some 8-bit MCUs, such as the 68HC08, work quite well in this test. But their performance must be moderated because such MCUs can manage only one interrupt at the time and so cast off a complex arbitration phase. The interrupt management of the ST9+ is **one of the more advanced**, allowing **nested interrupts** with full **software programmable priorities** and **program priority level control**.

Code efficiency results for interrupt processing performance are not really significant. The code represents only a very small part of an entire interrupt service routine, and so no conclusion can be made.

4.2.3 Conclusion

Global results and all its characteristics allow the ST9+ to **compete with the true 16-bit MCUs** on 8-bit and low-end 16-bit applications, and confirm its position of **high-end 8/16-bit MCU**.

MCU	Strong) points	Weak	c points
	instruction processing: fast 8/16-bit ALU:	7-byte prefetch queue predecoding 16-bit datapath	address alignment:	even jump/branch address even word operand address NOP instructions in assembly
80C51XA (20 MHz)	short average ICT: special addr. modes: special instructions: multitasking: large memory space: interrupt processing:	600 ns 8x8 multiplication 250 to 300 ns indirect with 8/16 offset or auto-increment compare & branch like decrement & branch like memory-to-memory moves context switching capabilities up to 16 Mbytes nested mode	lacking addr. modes:	code no indexed addressing
	interrupt proceeding.	4-bit program priority register programmable priority levels		
	instruction processing:	3-stage prefetch queue	address alignment:	performance penalty if odd
	fast 8/16/32-bit ALU: short average ICT:	16-bit datapath 625 ns 8x8 multiplication 375 to 440 ns	instruction lengths: lacking addr. modes: lacking instructions:	no direct addressing index register manipulation
68HC16 (16 MHz)	special addr. modes: special instructions: multitasking: large memory space:	with 8-bitoffset memory-to-memory moves context switching capabilities up to 1 Mbyte up to 16 Mbytes with memory		decrement & branch like
	interrupt processing:	expansion module nested mode 3-bit program priority register programmable priority levels		
	instruction processing:	2-stage prefetch queue predecoding	multitasking:	need memory expansion module
	fast 8/16-bit ALU:	20-bit datapath 375 ns 8x8 multiplication	interrupt processing:	one interrupt at a time recommended
68HC12 (8 MHz)	special addr. modes:	auto-incr/decrement indexed accumulator offset indexed		hardware fixed priorities
	special instructions: large memory space:	memory-to-memory moves incr/decrement & branch like test & branch like up to 4 Mbytes with memory expansion module		
	instruction encoding: short average IL: special addr. modes: special instructions:	risc-like encoding 2 to 3 bytes register indirect, 16-bit offset or pre/post-increment block moves	instruction processing: medium 8/16-bit ALU: medium average ICT: lacking instructions:	standard (no prefetch) 1400 ns 8x8 multiplication 500 to 600 ns 16-bit shifts/rotations compare & branch like
H8/300 (10 MHz)			multitasking: memory space: interrupt processing:	decrement & branch like no special capabilities 64 kbytes one interrupt at a time recommended no program priority register hardware fixed priorities

Table 3. High-end to low-end MCU strong and weak po	oints
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MCU	Strong	points	Weak	c points
68HC11 (4 MHz)			instruction processing: medium 8/16-bit ALU: long average ICT: lacking instructions: multitasking: memory space: interrupt processing:	standard (no prefetch) 2500 ns 8x8 multiplication 1500 to 1750 ns compare & branch like decrement & branch like no special capabilities 64 kbytes one interrupt at a time recommended no program priority register hardware fixed priorities
68HC08 (8 MHz)	instruction processing: fast 8-bit ALU: special addr. modes: special instructions:	1-byte prefetch queue 8-bit datapath 625 ns 8x8 multiplication indexed with 8-bit offset or post-increment memory-to-memory moves compare & branch like decrement & branch like up to 4 Mbytes with memory	medium average ICT: lacking addr. modes: multitasking: interrupt processing:	500 to 625 ns no indirect addressing no special capabilities one interrupt at a time recommended no program priority register hardware fixed priorities
	large memory space:	expansion module		

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Table 3. High-end to low-end MCU strong and weak points (cont'd)

4.3 MEDIUM-END TO LOW-END MCU ANALYSIS VERSUS ST7

The Table 4 presents the strong and the weak points for medium-end to low-end MCUs, compared to the ST7 MCU.

Notes: ICT means Instruction Cycle Time and IL means Instruction Length.

Refer to paragraph <Italic>7.2.2 Average ICT/CPI and IL<Italic end> for details on calculation.

Refer to paragraph <Italic>7.3.9 ST7 MCU core<Italic end> to see the main characteristics of the ST7 MCU core.

4.3.1 Computing performance results

Regarding speed, the ST7 MCU takes **the second position** just below the newly arrived 68HC08. With no prefetch mechanism, it comes even so ahead of all the other MCUs. A **short clock per instruction** added to a standard frequency explains its short instruction cycle time and its advantageous position. The two index registers and the indirect addressing mode allow the ST7 to easily perform **data manipulation** like **table manipulation** and **block move**. A direct addressing mode in a 256-byte zero page give a **rapid access to important data and peripheral registers**.

Concerning code efficiency, the ST7 MCU ranks **among the 8-bit MCUs**, very closely above the 68HC08. A standard instruction length explains its average position.

4.3.2 Interrupt processing performance results

Regarding speed, the ST7 MCU ranks **very close to the 68HC08**. A longer instruction cycle time explains this tiny gap. The strong point of its interrupt management is the **automatic stacking** of the cpu state, accumulator and index register. This process eliminates software stacking, and so saves time and space.

Code efficiency results for interrupt processing performance are not really significant. The code represents only a very small part of an entire interrupt service routine, and so no conclusion can be made.

4.3.3 Conclusion

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Global results and all its characteristics confirm the ST7 as an outstanding 8-bit MCU.

MCU	Strong	points	Weak points	
68HC11 (4 MHz)			medium 8/16-bit ALU: long average ICT: lacking instructions: multitasking:	2500 ns 8x8 multiplication 1500 to 1750 ns compare & branch like decrement & branch like no special capabilities
68HC08 (8 MHz)	instruction processing: fast 8-bit ALU: short average ICT: special addr. modes: special instructions: large memory space:	1-byte prefetch queue 8-bit datapath 625 ns 8x8 multiplication 500 to 625 ns indexed with 8-bit offset or post-increment compare & branch like decrement & branch like memory-to-memory moves up to 4 Mbytes with memory expansion module	lacking addr. modes: multitasking:	no indirect addressing no special capabilities
80C51 (20 MHz)	short average IL: special addr. modes: special instructions: multitasking:	1 to 2 bytes register indirect stack pointer relative compare & branch like decrement & branch like bit test & bit clear & jump memory-to-memory moves context switching capabilities	slow 8-bit ALU: long average ICT:	2400 ns 8x8 multiplication 900 to 1000 ns
KS88 (8 MHz)	special addr. modes: special instructions: multitasking: interrupt processing:	register pair indirect register/address indexed (short/long) compare & increment & branch like decrement & branch like context switching capabilities nested mode level priority control register	slow 8-bit ALU: long average ICT: data memory location:	3000 ns 8x8 multiplication 1250 to 1500 ns off-chip only
78K0 (10 MHz)	special addr. modes: special instructions: multitasking:	register indirect stack pointer relative indexed with 8-bit offset decrement & branch like context switching capabilities	mixed architecture: slow 8-bit ALU: long average ICT:	only accumulator oriented 3200 ns 8x8 multiplication 1400 to 1600 ns

Table 4. Medium-end to low-end MCU strong and weak points

5 DESCRIPTION OF MCU WORK ENVIRONMENTS

This section is a short description of the work environment, with the tools used (hardware and software tools), for each MCU during the benchmarks.

5.1 80C51XA MCU TOOLS

Hardware tools	P51XAG35 chip P51XADB/E development board/emulator Note that no external RAM was available on the development board.
Software tools	A Microsoft Windows based integrated development environment have been elaborated upon by Macraigor Systems Incorporated. The interesting tools for the benchmarks were a standard editor, an XA absolute macro assembler, and an emulator interface/debugger.

5.2 68HC16 MCU TOOLS

Hardware tools	MC68HC16Z1 chip M68HC16Z1EVB evaluation board Jumpers are set to configure the board.
	Note that, to access the I/O pin used for execution time measuring, a context switch is needed and add to each test routine 6 bytes and 375 ns. This length and time have been subtracted from measured results, in order not to disadvantage this MCU. If they are taken into account, the computing performance results are just a little worse (1.40) but code efficiency decreases down to 1.45. Note that the external RAM of the evaluation board needs wait states and so was not use.
Software tools	MASM16 (DOS environment) is an integrated environment for writing, editing assembling and debugging source code. It also allows to set the assembler options which are:
	masm -l'name'.lst -o'name'.o -a -b 'name'.asm >_masm16.err
	EVB16 is a DOS debugger for 68HC16Z1EVB.

5.3 68HC12 MCU TOOLS

Hardware tools	MC68HC812A4 chip M68HC12A4EVB evaluation board Jumpers have been left as configured in factory. Note that the external RAM of the evaluation board needs wait states and so was not use.
	The development of the routines is performed within an Integrated Development Environment (IDE) : Motorola MCU software. In a Windows environment, this software brings a project manager (MCU project), a macro-assembler (MCU asm), and a Motorola S-record generator (hex). The compilation options are: masm -y -W3 - I 'name'. Ist -a -o 'name'. o 'name'. a sm
Software tools	hex -F'name'.hex 'name'.o
Soltware 1001s	A communications program is then necessary to connect the PC to the evaluation board through a RS232 serial link. We have used PROCOMM PLUS for Windows, but any other communications program can suit the link to the Evaluation Board and its D-Bug12 monitor/ debugger program, resident in external EPROM.
	Note that the 'TBNE', 'TBEQ', 'DBNE', 'DBEQ', 'IBNE', and 'IBEQ' instructions were not usable without problems with the board used.

5.4 ST9+ MCU TOOLS

Hardware tools	ST90R192 chip Circuit Real Time Emulation System ST9+ HDS2 (Hardware Development System 2) The PLL clock has been used (see configuration in assembly codes)						
	The GNU C Toolchain (GCC9) for the ST9+ is used to assemble the code sources (in assembler language). The command line with its options is:						
	gcc9 -v -g -c -o 'name'.o 'name'.st9						
	Then it is linked with the linker LD9:						
Software toole	Id9 -I -i -m -Tdata 0x10000300 -o 'name'.u 'name'.o						
Software tools	To debug the program, the Windows Debugger WGDB9xxx for ST9+ is used together with the emulator. Here, the configuration file <i>hardware.gdb</i> is the following one:						
	clear_map						
	map 0x000000 32 sw						
	map 0x008000 16 sr						

5.5 ST9 MCU TOOLS

Hardware tools	ST90R50 chip Circuit Real Time Emulation System ST9 HDS2 (Hardware Development System 2)							
Software tools	The GNU C Toolchain for ST9 is used. The options are the following ones: gcc9 -v -g -c -o 'name'.o 'name'.st9 Id9 -I -i -m -Tdata 0x10000300 -o 'name'.u 'name'.o The Windows Debugger WGDB9xxx is used with the configuration file hardware.gdb : bankswitch off pd_signal used sdb sr ea 3<<2 sdb sr fc 08 sdb sr fd 08 sdb sr fe 00 # Mapping of memory map p:0x0000 0x7FFF SR map D:0x0000 0x7FFF SW							

5.6 H8/300 MCU TOOLS

Hardware tools	H8/330 chip LEV8330 evaluation board Default jumpers' settings have been kept. Note that the code was placed on external memory (the size of internal RAM is limited to 512 bytes). As the access to external memory is 3 times longer than the access to internal memory, the measured execution time results have been corrected. For each test, a value, equals to (200ns x number of bytes executed), has been subtracted (200ns for each byte of code). Actually, only the instruction fetch was wrong, and it lasted 300ns instead of 100ns for each byte.
Software tools	The Eurodesc H-series Interface Software (INTFC3) allows the user to communicate with the Hitachi's Executive Monitor System (EMS) located on the development board. It uses a DOS environment.

5.7 68HC11 MCU TOOLS

Hardware tools	MC68HC11A8 chip MC68HC11A8EVM evaluation board Note that the internal chip frequency on evaluation board was 2 MHz, but as 4 MHz versions are available, this frequency was used for results (execution time values have been divided by 2). Note that it was not possible to emulate external RAM.
Software tools	The integrated assembler IASM11 (DOS environment) allows to blend an editor and a cross assembler into one single environment. A DOS environment is used to debug programs.

5.8 68HC08 MCU TOOLS

Hardware tools	MC68HC708XL36 chip EML08XL36 emulator module plugged in the M68MMEVS05 modular evaluation system (platform board for EML08XL36) Jumpers configure both.							
	Rapid, a software development tool in a DOS environment allows to execute all the operations. It consists of a configuration program (Rinstall) and a cross assembler (CASM). Rinstall contains a serie of data entry screens. Only CASM and the MMEV08X DOS debugger were configured as follows:							
	 Cross assembler configuration: "CASM assembler" entry screen 							
	Name and fully path: 'path_of_CASM08.exe'							
	Primary options: <i>S L D</i>							
Software tools	Secondary options: S L D I							
	 Debugger configuration: "Debugger" entry screen 							
	Fully path: 'path_of_MMEVS08.exe'							
	Options: -B							
	Note that the assembler does not seem to manage the zero page addressing mode. Thus, the results have been modified to take this addressing mode into account. Without zero paraddressing mode, the execution time result changes to 0.61 and the code size result increase up to 1.43.							

5.9 ST7 MCU TOOLS

	ST7275 chip ST7 HDS (Hardware Development System) emulator with ST7275 DBE (Dedicated Board Emulator)
nardware tools	Note that measures have been made with a 4 MHz MCU, but as 8 MHz versions exist, two values are presented with the two frequencies (for the 8 MHz version, execution time values have been divided by 2).
	The toolchain used for the ST7 includes a meta-assembler (ASM), a generic linker (LYN), and a generic formatter (OBSEND). These software tools are used with the following options :
	asm -sym -li 'name'
Software tools	lyn 'name'
	asm 'name' -fi = 'name'.map
	obsend 'name', f, 'name'.s19, srec
	The Windows environment is used by the debugger: Windows Debugger WGDB7.

5.10 80C51 MCU TOOLS

	P80C32GBPN chip MicroTek EASYPACK 8051 serial emulator
Hardware tools	Note that the internal chip frequency on evaluation board was 12 MHz, but as 20 MHz versions are available, this frequency was used for results (execution time values have been divided by 20/12).
Software tools	IAR 8051 assembler

5.11 KS88 MCU TOOLS

Hardware tools	KS880504 and KS880116 chips SMDS II in-circuit emulator (Samsung Microcontroller Development System 2) with target boards TB880504A and TB880116A A function generator has been used to reach the 8 MHz frequency. It has been connected to the Personality Board in the SMDS2 emulator after having selected the EXTRA clock source with the switches in the front panel.
	Note that this MCU do not own any internal RAM - register file space excepted. It was also impossible to emulate external memory. Tests have been performed using register file only.
	Everything is done from the SMDS operating program software (DOS environment). SAMA (Samsung Assembler) is used to assemble the programs with the following command line and options:
Soltware tools	SAMA.EXE %S /K /LST
	Then, the program is loaded to SMDS2 memory (emulation memory) and a work file is made ([M] key). The debugging screen is accessed with the [D] key.

5.12 78K0 MCU TOOLS

Hardwara taala	µPD78P014 chip 78K0 starter kit
Hardware loois	
	Note that it was not possible to emulate external RAM.
	The μ PD78P014 toolchain consists of a Micro Series assembler (A78000) and a Micro Series generic linker (XLINK). The command lines are as follows:
	A78000 'name'.asm 'name'.lst
	xlink 'name' -o 'name'.o -f bench.xcl
	The file <i>bench.xcl</i> extends the length of xlink command line. The extra options included in <i>bench.xcl</i> are:
	-c78000
Software tools	-Fnec
	-Z(CODE)INTVEC=8000
	-Z(CODE)CODE=8080
	-Z(DATA)DATA=FB00
	-Z(DATA)WRKSEG,SHORTAD=FE20-FEDF
	-Z(BIT)BITVARS=0
	-Y2
	The 78K0 starter kit has a DOS environment.

6 COMPLETE NUMERICAL RESULTS

Here are the tables with the complete numerical results.

6.1 CORE COMPUTING PERFORMANCE

The first two tables (Table 5 and Table 6) concern **execution time** with the values measured in milliseconds and the ratios calculated with ST9+ MCU as reference. The next two tables (Table 7 and Table 8) concern **code size** with the values measured in bytes and the ratios calculated with ST9+ MCU as reference. The last two tables (Table 9 and Table 10) present global execution time ratios and global code size ratios with reduced and full set of tests.

Refer to section 9 for measurement proceeding and calculation description.

Notes: The reduced set of tests includes string, char, bubble(10 words), blkmov(64 bytes), convert, 16mul, shright, bitrst tests. They are in **boldface** characters.

Numbers with parenthesis have been judged out of range and have not been taken into account. In fact, it means that this specific test was absolutely unadapted to this specific MCU. Only some tests, which are not include in the reduced set, are concerned.

Legend:		x.xx	best results			
	▼	x.xx	worst results			

6.2 CORE INTERRUPT PROCESSING PERFORMANCE

Table 11 concerns **execution time** with the values measured in microseconds, showing interrupt latency & return time, the total time, and the ratios calculated with ST9+ MCU as reference. Table 12 concerns **code size** with the values measured in bytes and the ratios calculated with ST9+ MCU as reference.

The execution time has only been calculated **theoretically** with the assembly code, like computing performance theoretical execution time (see <ltalic>9.1.1 Execution time measure<ltalic end>). The result is the sum of the **interrupt latency** (execution time of the longest instruction and interrupt entry time) and the **execution time** of the interrupt service routine. The code size has been calculated with the assembly code.



	Execution time measures (ms)	80C51XA (20 MHz)	68HC16 (16 MHz)	68HC12 (8 MHz)	ST9+ (25 MHz)	ST9 (12 MHz)	H8/300 (10 MHz)	68HC11 (4 MHz)	68HC08 (8 MHz)	ST7 (8 MHz)	ST7 (4 MHz)
1	sieve	▲ 25.1	27.8	47.5	41.4	142	147				
2	acker(3,5)	▲ 148	224	230	268	868	916	950			
3	acker(3,6)	▲ 602	920	936	1,090	3,530	3,720	3,850			
4	string	0.178	0.157	▲ 0.15	0.160	0.514	0.369	0.54	0.264	0.345	0.690
5	char	0.042	0.039	▲ 0.037	0.048	0.149	0.071	0.140	0.039	0.0070	0.140
6	bubble(10 words)	▲ 0.170	0.223	0.328	0.306	0.988	0.741	1.33	1.14	1.09	2.18
7	bubble(600 words)	▲ 638	968	1,280	1,190	3,830	3,750	5,130		4,280	▼ 8,560
8	blkmov(64 bytes)	▲ 0.025	0.035	0.037	0.057	0.174	0.036	0.259	0.078	0.153	0.305
9	blkmov(512 bytes)	▲ 0.167	0.272	0.289	0.452	1.36	0.261	2.05		1.34	2.67
10	convert	▲ 0.146	0.227	0.288	0.223	0.766	0.397	0.82	0.265	0.452	0.904
11	16mul	0.0019	0.0017	▲ 0.0016	0.0068	0.020	0.012	0.029	0.013	0.018	0.037
12	shright	▲ 0.0013	0.0038	0.0046	0.0034	0.011	0.010	0.017	0.0072	0.010	0.020
13	bitsrt	▲ 0.047	0.050	0.055	0.059	0.178	0.071	0.215	0.086	0.092	0.183

Table 5. Computing performance execution time measures

(1) The 80C51 results are preliminary results. They may changed in later versions.

Table 6. Computing performance execution time ratios

	Execution time ratios	800 (20	C51XA MHz)	68HC16 (16 MHz)	68 (8	HC12 MHz)	ST9+ (25 MHz)	ST9 (12 MHz)	H8/300 (10 MHz)	68HC11 (4 MHz)	68HC08 (8 MHz)	ST7 (8 MHz)	ع (4	ST7 MHz)	
1	sieve		1.65	1.49		0.87	1.00	0.29	0.28						I
2	acker(3,5)		1.81	1.20		1.16	1.00	0.31	0.29	0.28					
3	acker(3,6)		1.81	1.18		1.16	1.00	0.31	0.29	0.28					
4	string		0.90	1.02		1.05	1.00	0.31	0.43	0.30	0.61	0.46		0.23	
5	char		1.14	1.23		1.28	1.00	0.32	0.67	0.34	1.23	0.68		0.34	
6	bubble(10 words)		1.80	1.37		0.93	1.00	0.31	0.41	0.23	0.27	0.28		0.14	
7	bubble(600 words)		1.87	1.23		0.93	1.00	0.31	0.32	0.23		0.28	▼	0.14	
8	blkmov(64 bytes)		2.30	1.65		1.56	1.00	0.33	1.57	0.22	0.74	0.38		0.19	
9	blkmov(512 bytes)		2.71	1.66		1.56	1.00	0.33	1.73	0.22		0.34		0.17	
10	convert		1.54	0.98		0.78	1.00	0.29	0.56	0.27	0.84	0.49		0.25	
11	16mul		3.60	3.92		4.22	1.00	0.35	0.56	0.23	0.52	0.37		0.19	
12	shright		2.67	0.92		0.75	1.00	0.30	0.35	0.20	0.48	0.34		0.17	
13	bitsrt		1.25	1.18		1.08	1.00	0.33	0.83	0.27	0.69	0.65		0.32	

	Code size measures (bytes)	80C51) (20 MH	(A z)	68HC16 (16 MHz)	68 (8	HC12 MHz)	S ⁻ (25	T9+ MHz)	ST (12 M	「9 /IHz)	H8/3 (10 N	300 /Hz)	68HC1 (4 MH	1 z)	68H (8 N	IC08 /IHz)	S (8 I	ST7 MHz)	S (4	GT7 MHz)
1	sieve	4	49	68		73		48		48		54								
2	acker(3,5)		73	68		62		88		88		86		80						
3	acker(3,6)		73	68	-	62		88		88		86		80						
4	string	ļ	57	52	-	43		50		50		52		54		61		53		53
5	char		31	26		21		29		29		28		20		22		22		22
6	bubble(10 words)	4	41	44		40		44		44		42		57		106		88		88
7	bubble(600 words)	4	41	44		40		44		44		42		57				(764)		(764)
8	blkmov(64 bytes)		18	20		15		17		17		12		13		13		14		14
9	blkmov(512 bytes)		18	20		19		17		17		24		13			▼	44	►	44
10	convert	2	24	▼ 32		22		23		23		22		29		14		22		22
11	16mul		10	10	•	7		44		44		40		62	▼	66	▼	66	►	66
12	shright		8	14		11		10		10		12		14	▼	16		15		15
13	bitsrt	34	40	304		310		261		261		138	2	33		260		290		290

Table 7. Computing performance code size measures

(1) The 80C51 results are preliminary results. They may changed in later versions.

Table 8. Computing performance code size ratios

	Code size ratios	80C51XA (20 MHz)	68HC16 (16 MHz)	68 (8	HC12 MHz)	S (25	ST9+ SMHz)	؛ 12(ST9 MHz)	H8/ (10 I	300 VHz)	68H (4 N	IC11 /IHz)	68I (8	HC08 MHz)	9 (8)	ST7 MHz)	9 (4	ST7 MHz)
1	sieve	1.02	1.42		1.52		1.00		1.00		1.13								
2	acker(3,5)	0.80	0.77		0.71		1.00		1.00		0.98		0.91						
3	acker(3,6)	0.83	0.77		0.71		1.00		1.00		0.98		0.91						
4	string	1.14	1.04		0.86		1.00		1.00		1.04		1.08		1.22		1.06		1.06
5	char	1.07	0.90		0.720		1.00		1.00		0.97		0.69		0.76		0.76		0.76
6	bubble(10 words)	0.93	1.00		0.91		1.00		1.00		0.96		1.30		2.41		2.00		2.00
7	bubble(600 words)	0.93	1.00		0.91		1.00		1.00		0.96		1.30				(17.4)		(17.4)
8	blkmov(64 bytes)	1.06	1.18		0.88		1.00		1.00		0.71		0.77		0.77		0.82		0.82
9	blkmov(512 bytes)	1.06	1.18		1.12		1.00		1.00		1.41		0.77			►	2.60	▼	2.60
10	convert	1.04	1.40		0.96		1.00		1.00		0.96		1.26		0.61		0.96		0.96
11	16mul	0.23	0.23		0.16		1.00		1.00		0.91		1.41	►	1.50	►	1.50	▼	1.50
12	shright	▲ 0.80	1.40		1.10		1.00		1.00		1.20		1.40	▼	1.60		1.50		1.50
13	bitsrt	1.30	1.17		1.19		1.00		1.00		0.53		0.89		1.00		1.11		1.11

Global execution time ratios	80C (20	51XA MHz)	68HC16 (16 MHz)	68HC12 (8 MHz)	ST9+ (25 MHz)	ST9 (12 MHz)	H8/300 (10 MHz)	68HC11 (4 MHz)	68HC08 (8 MHz)	ST7 (8 MHz)	ST7 (4 MHz)
with reduced set of tests		1.90	1.54	1.46	1.00	0.32	0.67	0.26	0.67	0.46	0.23
with full set of tests		1.92	1.47	1.33	1.00	0.32	0.64				

Table 9. Computing performance global execution time ratios

(1) The 80C51 results are preliminary results. They may changed in later versions.

Table 10. Computing performance global code size ratios

Global code size ratios	80C51XA (20 MHz)	68HC16 (16 MHz)	68 (8	HC12 MHz)	ST9+ (25 MHz)	ST9 (12 MHz)	H8/300 (10 MHz)	68HC11 (4 MHz)	68HC08 (8 MHz)	ST7 (8 MHz)	ST7 (4 MHz)
with reduced set of tests	0.95	1.04		0.85	1.00	1.00	0.98	1.10	1.24	1.21	1.21
with full set of tests	0.94	1.03		0.90	1.00	1.00	1.04				

(1) The 80C51 results are preliminary results. They may changed in later versions.

Table 11. Interrupt processing performance execution time values and ratios

Execution time values (µs) and ratios	80C51XA (20 MHz)	68HC16 (16 MHz)	68HC12 (8 MHz)	S (25	ST9+ MHz)	ST9 (12 MHz)	H8/300 (10 MHz)	68 (4	BHC11 MHz)	68HC08 (8 MHz)	ST7 (8 MHz)	ST7 (4 MHz)
interrupt latency & return	3.15	4.19	3.75		2.40	7.17	3.90	•	21.75	2.88	3.88	7.75
execution time values	4.70	7.56	6.25		4.08	12.00	8.70	▼	17.25	5.25	6.50	13.00
execution time ratios	0.87	0.54	0.65		1.00	0.34	0.47	▼	0.19	0.78	0.63	0.31

Table 12. Interrupt processing performance code size values and ratios

Code size values and ratios	80C51XA (20 MHz)	68HC16 (16 MHz)	68HC12 (8 MHz)	ST9+ (25 MHz)	ST9 (12 MHz)	H8/300 (10 MHz)	68HC11 (4 MHz)	68HC08 (8 MHz)	ST7 (8 MHz)	ST7 (4 MHz)
code size values (bytes)	28.5	▼ 36	16.5	19.5	19.5	33	▲ 13.5	16	16.5	16.5
code size ratios	1.46	▼ 1.85	0.85	1.00	1.00	1.70	▲ 0.69	0.82	0.85	0.85

7 MCU CORE ARCHITECTURE ANALYSIS

This section presents, for the different MCUs, the **main parameters of the core architecture** which are significant for benchmark result analysis.

7.1 PARAMETER DESCRIPTION

The significant parameters of core architecture are the following ones:



7.2 REMARKS ON SOME PARAMETERS

7.2.1 Instruction processing

Only two different instruction processings exist:

- standard processing: current instruction is completely processed before next one is fetched
- prefetch mechanism: some next opcodes are prefetched as current instruction is processed

The **prefetch mechanism** is best described **as a queue** rather than as a pipeline. Queue logic fetches program information and positions it for execution, but instructions are executed sequentially. A typical pipelined CPU executes more than one instruction at the same time. The **queue size** is given, but **performance** is not precised because no value is given by databooks. Nevertheless, general statistics on instruction processing mechanisms give an usual average **20%-25% gain for one stage**, and this gain is not more than **25%-30% for two stages**. Additional stages without complex mechanisms do not give higher gain. Anyway, the instruction processing mechanism has a leading role in general performance.

7.2.2 Average ICT/CPI and IL

The average ICT (Instruction Cycle Time) is a currently used parameter. But it is linked to the frequency f, then we prefer the **average CPI** (Clock Per Instruction) to **describe the instruction set**. On the other hand, to **compare MCU core performance**, the frequency has to be considered, and so the **average ICT** is used in result analysis (section 4). Charts with ICT and IL ranges are presented at the end of this section (see <ltalic>7.4 Instruction Cycle Time chart<ltalic end> and <ltalic>7.5 Instruction Length chart<ltalic end>).

Remark that the average ICT (in μ s) is the inverse of the MIPS parameter (Million Instruction Per Second), and so we have the formula:

$$MIPS = \frac{f}{CPI} = \frac{1}{ICT}$$

(f is in MHz and ICT is in μ s)

The **average ICT/CPI** and **average IL** have been calculated considering **all available instructions** and **all possible addressing modes**, **favouring mostly used ones** in the test routines. Ranges are presented instead of decimal values, to take the subjectivity of the calculation into account. Thus the values can be considered as reliable.

7.2.3 Special addressing modes and instructions

Test routines assembly code analysis has pointed out that some addressing modes and instructions can reduce significantly the code size. To a minor extent, execution time may also be decreased. The addressing modes and instructions concerned are usually those which allow to make two operations within a single instruction.

Indirect with pre/post-increment addressing mode is an example. This mode is very useful for loops and block moves. Modes allowing memory-to-memory transfers are another example for block moves. In the same way, instructions such as bit test & set, decrement & branch, or compare & branch have stood out for the same reasons.

These addressing modes and instructions are mentioned in tables as **special addressing mode**s and **special instructions**.

7.3 MCU CORE ANALYSIS

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The following paragraphs are **synthetical diagrams** presenting the **main parameters** of core architecture for each MCU. Those parameters have been synthesized from the databooks. Some special characteristics are also mentioned, even if they are not really significant for the benchmark result analysis.

7.3.1 80C51XA MCU core

7.3.2 68HC16 MCU core

7.3.3 68HC12 MCU core

7.3.4 ST9+ MCU core

7.3.5 ST9 MCU core

7.3.6 H8/300 MCU core

7.3.7 68HC11 MCU core

7.3.8 68HC08 MCU core

7.3.9 ST7 MCU core

Programming model Accumulator - one 8-bit accumulator - two 8-bit index registers - other registers 16-bit program counter 16-bit stack pointer condition code register	LD (X),A Instruction set ADD A,#A0 Cisc encoding - CPI 2 cycles to 12 cycles - average CPI between 4 and 5 cycles - IL 1 byte to 4 bytes - average IL between 2 and 3 bytes - special addressing modes indirect (short/long)
ST7 CPU	buses 16-bit address bus, 8-bit data bus (to be confirmed)
Instruction processing Standard - sequential processing	Arithmetic Logic Unit + x 8-bit datapath - 8-bit operations - special functions 8x8 unsigned multiplication 11 cycles
On-chip/Off-chip buses - on-chip buses 16-bit address bus 8-bit data/program memory bus	Memory Space Von Neumann organization Ilinear data/program memory space 64 kbytes 256-byte zero page 128-byte peripheral register space direct addressable upper 32-byte interrupt vector table = 14 interrupts

7.3.10 80C51 MCU core

7.3.11 KS88 MCU core

7.3.12 78K0 MCU core

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7.4 INSTRUCTION CYCLE TIME CHART

The following chart (Figure 6.) presents complete and average Instruction Cycle Time (ICT) ranges for the different MCUs.

The complete range goes from the minimum to the maximum complete ICT. The average ICT range goes from the minimum to the maximum average ICT. For explanation on calculation, see see https://www.see.org see <a href="htt

7.5 INSTRUCTION LENGTH CHART

The following chart (Figure 7.) presents complete and average Instruction Length (IL) ranges for the different MCUs.

The complete range goes from the minimum to the maximum complete IL. The average ICT range goes from the minimum to the maximum average IL. For explanation on calculation, see ttalic>7.2.2 Average ICT/CPI and IL ttalic end>.

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8 DESCRIPTION OF THE TEST ROUTINES

This section is a more precise description of the test routines. For each test, are detailed the algorithm, its implementation and the features which it stresses.

8.1 ERATOSTHENES SIEVE

Algorithm	The <i>Eratosthenes sieve</i> is a well-known algorithm which searches the prime numbers greater than or equal 3 out of n elements (n=8189 has been chosen arbitrary).
	The even numbers greater than 3 are not prime numbers, so that this algorithm only looks for prime numbers among an array of odd numbers.
Implementation	We have chosen an array of 8189 elements. It represents the odd numbers from 3 to 16379. The array is initialized with the value 'true' ('true' = 0), and is then filled with 1 (false) if the corresponding number is not a prime number or is not modified (it keeps the value 0='true') if it is a prime number. Don't forget that it is an array of odd numbers: $array[j] \leftrightarrow 2j+3$
	At the beginning of the routine, each number is a potential prime number (initialization value is 'true'). The algorithm consists in setting (to 'false') the odd multiples of every prime number found in the array skimmed through in the ascending order.
Features stressed	This test measures the elementary computational capability and the ability to manipulate data in an array .

8.2 ACKERMANN FUNCTION

Algorithm	The Ackermann function is a two parameter function -acker(m,n)- which induces several recursive calls.
Implementation	This test routine is performed with two different pairs of parameters: $acker(3,5)$ and $acker(3,6)$. For instance, with the parameters m=3 and n=6, the function induces 172, 233 procedure calls.
Features stressed	It tests the efficiency in recursive procedure calls and in stacks usage.

8.3 STRING SEARCH

Algorithm	The String search consists in searching a 16-byte string in a 128-character array.
Implementation	The data are predefined with the following contents: for the 128-character array, "xxxxxxxpatterxxxxxxxxxxxxxxxxxxxxxxxxxxxxxxxxxxx
Features stressed	This program measures the efficiency in data comparison and string manipulation.

8.4 CHARACTER SEARCH

Algorithm	The Character search consists in searching a byte in a 40-byte block.
Implementation	The data are also predefined. The algorithm searches the byte "o" in the 40-byte block "ooo", where the character 'o' is the 32 nd character of the block.
Features stressed	As the string search, this program measures the efficiency in data comparison.

8.5 BUBBLE SORT

Algorithm	The Bubble sort benchmark manages the sorting of a one dimension array of 16-bit integers.		
Implementation	The test is performed with 10 words and then with 600 words. The array is initialized with 10 or 600 words (16-bit integers) in reverse order.		
	The algorithm is a classic bubble sort which arranges the 10 words (or the 600 words) in the ascending order of magnitude.		
	Note that the routine used is intentionally almost the same for the two values (as though it could have been optimized for the first value). Few differences may exist, but they do not modify the way the test is done.		
Features stressed	ed This benchmark demonstrates the efficiency in data comparison and data manipulation especially in 16-bit value comparison and 16-bit value manipulation.		

8.6 BLOCK MOVE

Algorithm	The <i>Block move</i> test routine aims at transferring a block from a place to another place in memory.		
Implementation	This program is tested with a 64-byte block and with a 512-byte block. Note that the routine used is intentionally almost the same for the two values (as though it could have been optimized for the first value). Few differences may exist, but they do not modify the way test is done.		
Features stressed	It shows the data blocks manipulation ability.		

8.7 BLOCK TRANSLATION

Algorithm	The <i>Convert</i> test routine aims at transferring a block from a place to another place in memory.		
Implementation	It uses a table to convert the source block into the destination block. The table contains the translation of the source block elements. This benchmark is useful to convert for example from an ASCII code to an EBCDIC code		
Features stressed	As the block move test program, it shows the data blocks manipulation ability , but also the ability to use a lookup table .		

8.8 16-BIT INTEGER MULTIPLICATION

Algorithm	The <i>16-bit integer multiplication</i> program performs a multiplication of two unsigned words (16-bit integers), giving a 32-bit result.	
Implementation	The two operands chosen here are 256, so that the multiplication performed is: 256 x 256 = 65536 (=10000h hexadecimal value)	
Features stressed	This test measures the computational capability of the microcontroller with 16-bit integers .	

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Algorithm	The 16-bit value right shift routine shifts a 16-bit value five places to the right.	
Implementation	The operand to be shifted is 40h (hexadecimal value). It is taken into account as a 16-bit integer and it is the 16-bit value which is shifted.	
Features stressed	It is a test measuring the word (16-bit) and bit manipulation capability.	

8.9 16-BIT VALUE RIGHT SHIFT

8.10 BIT MANIPULATION

Algorithm	The <i>Bit manipulation</i> benchmark performs the set, the reset, and the test of 3 bits in a 128-bit array.			
	The memory where some bits will be set, reset, and tested, is initialized with the 'Ah' value (hexadecimal value). It is composed of 8 words '0AAAAh', which represents a 16-byte memory area, that is to say a 128-bit array.			
Implementation	The test consists in setting, resetting, and then testing the 10th bit of the array, then the 13th bit of the array, and then the 123 rd bit of the array. Setting a bit is setting it to 1. Resetting a bit is resetting it to 0. And testing a bit is testing it and setting it to 1 if zero (with the zero flag Z also set if zero).			
Features stressed	This benchmark measures the computational capability and the efficiency in bit manipulation .			

8.11 TIMER INTERRUPT

Algorithm	The <i>Timer interrupt</i> benchmark is composed of two routines performing an input capture interrupt and an input capture/output compare interrupt.			
Implementation	 The first routine is the body of an interrupt service routine handling a timer input capture. The second is the body of an interrupt service routine handling a timer input capture or a output compare; as interrupt vectors can be separate, this routine may be composed of two different parts. The routines include: the average instruction (that is an instruction lasting the average instruction cycle time) which is interrupted and the interrupt entry process (they represent the interrupt latency) the body of a typical interrupt service routine including the following operations: stack two registers or change register bank (if not done by interrupt processing) read timer register call to a subroutine with input capture register content as input parameter or output compare registers or restore register bank (if not done by interrupt processing) return from subroutine unstack registers or restore register bank (if not done by interrupt processing) return from interrupt It is true that each MCU has its specific own manner of handling interrupts. Reading the timer register and using the input capture/output compare as a parameter for a function call has been judged as a satisfying way to do so. Thus, it has been chosen as routine body. 			
Features stressed	This benchmark measures the interrupt processing performance.			

9 MEASUREMENT PROCEEDING AND CALCULATION

This section describes measurement proceeding and calculation for computing performance test routines only. Interrupt processing performance test routines are not concerned (see <ltalic>6.2 Core interrupt processing performance<ltalic end> for details on measure and calculation).

9.1 MEASUREMENT PROCEEDING

The parameters measured are **execution time** and **code size**. The first has been measured on MCU boards (thanks to an oscilloscope) whenever possible, or with the assembly code. The second has been measured on the assembly code.

To facilitate execution time measurement, assembly code has been divided in two parts. The first, called **Assignments & Initializations** in the source code, contains the initialization of the MCU and data and then a call to the test routine; which is included in the second part, called **Test Loop**. The first part ends with an infinite loop. The execution time and code size will obviously be measured on *Test Loop* part.

9.1.1 Execution time measure

An **I/O pin** is used to make the measure, thanks to a **digital oscilloscope**. This I/O pin is configured as an output, with a push-pull, and interrupts are disabled in the initialization part. The pin used for each MCU is detailed in Table 13.

MCU name	I/O pin for measure
80C51XA	pin 0 of port 2
68HC16	pin 2 of port E
68HC12	pin 7 of port E
ST9+	pin 0 of port 4
ST9	pin 0 of port 4
H8/300	pin 0 of port 6
68HC11	pin 0 of port B
68HC08	pin 0 of port A
ST7	pin 0 of port B
80C51	pin 0 of port 1
KS88	pin 0 of port 2 (for 88C0504) pin 0 of port 4 (for 88C0116)
78K0	pin 0 port 2

Table 13. I/O pins for execution time measuring

The Test Loop routine begins with the set of the I/O pin. This marks the beginning of the test

Theoretical execution time = internal clock frequency

routine and so the start of the measure on the oscilloscope (trigger on positive edge). The following lines are the implementation of the algorithm. This part ends with the reset of the I/O pin and a return of the call.

The **execution time** is the length of the pulse triggered with the oscilloscope. Figure 8. shows the diagram of the way of execution time measurement proceeding.

Note that it was sometimes not possible to implement all the tests on an MCU (see <ltalic>9.2.2 Memory considerations<ltalic end>). In some of these cases, test routines have even been written and execution time has been calculated **theoretically**. The theoretical execution time is simply given by dividing the number of clock cycles, calculated the assembly source, by the internal processing frequency:

Note that experience has shown the accuracy of these theoretical calculations in front of real measures. Thus results of both types can be compared.

Figure 8. Execution time measurement proceeding

9.1.2 Code size measure

Code size is measured with the assembly code. The result is the number of bytes used to code the test routine (in *Test Loop* part) without the set and reset instructions for the I/O pin.

Here is an example of a Test Loop:

0000	C290	test:	setb p1.0	; set I/O pin
0002 0004 0006 0009 000B 000C 000D 000E 000F 000F	7809 7982 900200 7F79 E6 93 F7 08 0A DFF9	loop:	mov r0, #srcpointer mov r1, #destpointer mov dptr, #200h mov r7, #121 mov a, @r0 movc a, @a+dptr mov @r1, a inc r0 inc r2 djnz r7, loop	; beginning of test routine ; end of test routine
0012 0014	D290 22	finish:	clr p1.0 ret	; reset I/O pin

The code size of this assembly code equals (12h-2h) = 10h = 16d, thus 16 bytes.

9.2 CALCULATION

9.2.1 Execution time and code size ratios

From execution time and code size measures, preliminary ratios with **ST9+ MCU as reference** have been calculated for each test. Using those results, a global execution time ratio and a global code size ratio have been calculated as an average of all ratios.

As all the tests could not have been implemented on all MCUs (see <ltalic>9.2.2 Memory considerations<ltalic end>), one or two different results are presented for each MCU. The first one, available for all the MCUs, has been calculated with the reduced set of tests performed on all the MCUs (Table 14). The second one, only available for some MCUs, has been calculated with the full set of tests (Table 15).

Table 14. Reduced set of tests

Tests concerned	string, char, bubble(10 words), blkmov(64 bytes), convert, 16mul, shright, bitrst		
Resulting ratio formulas <i>ET = execution time</i> <i>CS = code size</i>	Global ET ratio for reduced set =	sum(ET ratios of reduced set)	
		number of tests of reduced set	
	Global CS ratio for reduced set =	sum(CS ratios of reduced set)	
		number of tests of reduced set	

Tests concerned	string, char, bubble(10 words), blkmov(64 bytes), convert, 16mul, shright, bitrst sieve, acker(3,5), acker(3,6), bubble(600 words), blkmov(512 bytes)		
Resulting ratio formulas	Global ET ratio for full set =	sum(ET ratios of full set) number of tests of full set	
ET = execution time CS = code size	Global CS ratio for full set =	sum(CS ratios of full set) number of tests of full set	

9.2.2 Memory considerations

 ∇

The "**place**" of the memory (internal or external) of the MCU used for stack, has indirectly a consequence on the results. As all the MCUs own internal memory and do not own external memory, internal memory has been used for most of the tests. But because some tests (especially Ackermann function) require an important stack capacity, alternative solutions have been elaborated.

Here is a synthesis of the different cases:

- for tests with a limited memory need, internal memory has been used as stack
- for tests with important memory need,
 - for MCUs with important internal memory available, internal memory has been used
 - for MCUs with limited internal memory but with external memory (with identical access time) available, **external memory** has been used
 - for MCUs with limited internal memory and external memory with longer access time, no real measure has been made in order not to disfavour some MCUs; in some of these cases, theoretical measures have been calculated based on the assembly code - note that theoretical results are closed to practical results with internal memory

A small number of tests for some MCUs could not have been implemented due to various reasons.

As theoretical results are close to actual results with internal memory (see <Italic>9.1.1 Execution time measure<Italic end>), there are only two main cases (for each MCU):

- tests which have been performed (theoretically or practically with internal or external memory)
- tests which have not been implemented (due to various reasons)

As a matter of facts, there are two different sets of tests:

- the reduced set of tests performed on all the MCUs
- the full set of tests performed only on some MCUs

A rapid view on results show that the ratios obtained using both set of tests are not very different (see <ltalic>4.1 Preliminary remark<ltalic end>).

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